Heraeus

Conductors

TC7304A

Ag Via fill Paste for LTCC/ DPIS*

*** Development Product Information Sheet**

Description
TC7304A is a pure Ag via fill which provides excellent compatibility with Heratape® CT800 and CT70x during cofiring process.

TC7304A is optimized for stencil printing of vias.

The paste is compatible with other cofiring pastes and with various postfiring pastes.

Processing

1. Spatulate well prior to processing. The paste should have acquired room temperature before being opened, to avoid condensation.
2. Print through a stencil.
3. Level at room temperature for 5 - 10 minutes.
4. Dry at max. 80 °C for 10 – 30 minutes.
5. Fire at 850 ℃ – 865 ℃ (peak) for 10 minutes, a nd with a total firing cycle time up to 10 hours (is often most practicable in a box oven).

Thinner: HVS 507

Properties (Paste)

Form:	Thixotropic paste
Viscosity:	100 – 200 Pas, (25 °C, D = 15 s^{-1})
Solids:	90.0 +/- 1.0 %
Shelf Life:	12 months, with correct storage (5 – 25 ℃ in a cool, dry, dark place, and with the container tightly shut).

Properties (Fired)[1)]

Via Definition[2)]:	>80 µm
Resistivity [2)]:	≤ 0.02 mΩ x cm (FFT: 20 µm)

Compatibility

Dielectric	Heratape CT800, CT70x

1) Typical properties based on laboratory test methods. For optimum results all materials should be fired in a profiled furnace supplied with dried, hydrocarbon-free and other contaminant-free air.

2) Measured after printing with a steel stencil; thickness was approx. 100 µm, and the resultant printed geometry was 40 mm x 10 mm.

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The descriptions and engineering data shown here have been compiled by Heraeus using commonly-accepted procedures, in conjunction with modern testing equipment, and have been compiled as according to the latest factual knowledge in our possession. The information was up-to date on the date this document was printed (latest versions can always be supplied upon request). Although the data is considered accurate, we cannot guarantee accuracy, the results obtained from its use, or any patent infringement resulting from its use (unless this is contractually and explicitly agreed in writing, in advance). The data is supplied on the condition that the user shall conduct tests to determine materials suitability for a particular application.

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